

In the Claims

Please amend Claim 1 as follows.

1           1.    **(Currently Amended)** An integrated circuit ~~chip~~  
2   board, the ~~chip board~~ comprising:  
3           a ~~plurality multiplicity of components~~ semiconductor  
4   chips for processing signal groups, wherein a plurality of  
5   semiconductor chips exchange signal groups using wireless  
6   techniques, the multiplicity of semiconductor chips  
7   including; and  
8           ~~a group of components for~~ at least one selected  
9   semiconductor chip receiving wireless signal groups from at  
10   least one predetermined semiconductor chip on the circuit  
11   board, the group of components including; the selected  
12   semiconductor chips having:  
13           an antenna for receiving ~~radio frequency~~ wireless  
14   signals;  
15           a ~~radio frequency~~ wireless signal receiver  
16   coupled to the antenna, the receiver detecting the ~~radio~~  
17   ~~frequency~~ wireless signals; and  
18           a demodulator coupled to the receiver, the  
19   demodulator recovering signal groups in the ~~radio frequency~~  
20   wireless signals, ~~the signal groups being applied to the~~  
21   ~~plurality of components.~~

22  
23   **Please withdraw Claim 2.**

24  
25           2. **(Withdrawn; Non-Elected)** The chip as recited in  
26   claim 1 wherein the radio frequency signals are modulated

1 in a format selected from the group consisting of parallel-  
2 formatted signal groups and serial-formatted signal groups.

3  
4 **Please amend Claim 3 as follows.**

5  
6 3. **(Currently Amended)** The ~~chip~~ integrated circuit  
7 board as recited in claim 1 wherein signals received by the  
8 ~~radio-frequency wireless signal~~ receiver are modulated with  
9 a modulation from the group consisting of amplitude  
10 modulation and frequency modulation.

11  
12 **Please amend Claim 4 as follows.**

13  
14 4. **(Currently Amended)** The ~~chip~~ integrated circuit  
15 board as recited in claim 1 further including an analyzer,  
16 the analyzer receiving ~~signals~~ signal groups from the  
17 demodulator, the analyzer ~~decodes~~ decoding the signal from  
18 the demodulator into a plurality of logic signals.

19  
20 **Please withdraw Claim 5.**

21  
22 5. **(Withdrawn; Non-Elected Claim)** The chip as  
23 recited in claim 4 wherein the analyzer provides a  
24 parallel-data signal group for each demodulated signal in a  
25 series of demodulated signals.

1 Please withdraw Claim 6.

2

3 6. (Withdrawn; Non-Elected Claim) The chip as  
4 recited in claim 1 wherein the group of components further  
5 includes:

6 a modulator for modulating a radio frequency signal  
7 with signals from the plurality of components; and  
8 a transmitting unit for applying the modulated radio  
9 frequency signals to the antenna.

10

11 Please withdraw Claim 7.

12

13 7. (Withdrawn; Non-Elected Claim) The chip as  
14 recited in claim 6 wherein the transmitting unit is coupled  
15 to a second antenna.

16

17 Please amend Claim 8 as follows.

18

19 8. (Currently Amended) The chip integrated circuit  
20 board as recited in claim 1 wherein the signal groups  
21 include a header portion, a data portion, and a tail  
22 portion.

23

24 Please amend Claim 9 as follows.

25

26 9. (Currently Amended) A method for transferring  
27 logic signal groups between integrated circuit  
28 semiconductor chips, the method comprising:  
29 modulating and transmitting a radio frequency wireless  
30 signal by a first integrated circuit semiconductor chip,

1 the wireless signal being modulated with logic signal  
2 groups generated by the first integrated circuit  
3 semiconductor chip; and  
4 receiving and demodulating the radio frequency  
5 wireless signal by the a second integrated circuit  
6 semiconductor chip.

7  
8 **Please amend Claim 10 as follows.**

9  
10 10. **(Currently Amended)** The method as recited in  
11 claim 9 wherein the radio frequency wireless signal  
12 transmits signal groups formatted in a serial format.

13  
14 **Please withdraw Claim 11.**

15  
16 11. **(Withdrawn; Non-Elected Claim)** The method as  
17 recited in claim 9 wherein the radio frequency signal  
18 transmits signal groups formatted in a parallel format.

19  
20 **Please amend Claim 12 as follows.**

21  
22 12. **(Currently Amended)** The method as recited in  
23 claim 9 wherein the modulation of the carrier frequency  
24 wireless signal transmitting the signal groups is  
25 modulation modulated with a modulation selected from the  
26 group consisting or of amplitude modulation and frequency  
27 modulation.

1 Please amend Claim 13 as follows.

2  
3 13. (Currently Amended) The method as recited in  
4 claim 9 wherein a transmitted wireless signal is encoded  
5 with a signal identifying to identify a preselected pattern  
6 of signals.

7  
8 Please amend Claim 14 as follows.

9  
10 14. (Currently Amended) The method as recited in  
11 claim 13 wherein the receiving and demodulating of the  
12 wireless signal provide a decoded signal representing a  
13 preselected pattern of signals.

14  
15 Please amend Claim 15 as follows.

16  
17 15. (Currently Amended) A system for transferring  
18 data signal groups between integrated circuit semiconductor  
19 chips: the system comprising:

20 a first integrated circuit chip, the first integrated  
21 circuit at least one transmitting semiconductor chip  
22 including:

23 a first processing unit; and

24 a radio wireless transmitting unit coupled to the  
25 first processing unit and receiving signal groups there  
26 from, the radio wireless transmitting unit transmitting the  
27 signal groups from the first processing unit; and

28 a second integrated circuit, the second integrated  
29 circuit at least one receiving semiconductor chip  
30 including:

1           a second processing unit, and  
2           a radio wireless receiving unit coupled to the  
3 second processing unit, the radio wireless receiving unit  
4 receiving radio the signal groups from the transmitting  
5 unit, the transmitting unit receiving unit applying the  
6 signal groups to the second processing unit.

7  
8 **Please withdraw Claim 16.**

9  
10       16. **(Withdrawn; Non-Elected Claim)** The system as  
11 recited in claim 15 wherein the second integrated circuit  
12 includes a transmitting unit, and wherein the first  
13 integrated circuit chip includes a receiving unit, the  
14 first integrated circuit chip receiving unit adapted to  
15 receive the signals from the second integrated circuit  
16 transmitting unit.

17  
18 **Please withdraw Claim 17.**

19  
20       17. **(Withdrawn; Non-Elected Claim)** The system as  
21 recited in claim 15 wherein the signals groups are  
22 transmitted in a format selected from the group consisting  
23 of serial-formatted groups and parallel-formatted signal  
24 groups.

25  
26       18. **(Original)** The system as recited in claim 15  
27 wherein the transmitting unit semiconductor chip includes a  
28 synthesizer and the receiving unit semiconductor chip  
29 includes an analyzer for processing serial serially  
30 transmitted information signal groups.

1  
2 **Please amend Claim 19 as follows.**

3  
4 19. **(Currently Amended)** The system as recited in  
5 claim 15 wherein the first integrated circuit transmitting  
6 semiconductor chip is located on a first circuit board and  
7 the second integrated circuit receiving semiconductor chip  
8 is located on a second circuit board, the first circuit  
9 board and the second circuit board being in a stacked  
10 configuration.

11  
12 20. **(Original)** The system as recited in claim 15  
13 wherein the signal groups include a header portion, a data  
14 portion and a tail portion.

15  
16 **Please add Claim 21.**

17  
18 21. **(New)** The integrated circuit board as recited in  
19 claim 1 wherein the integrated circuit board is a  
20 semiconductor substrate, the semiconductor chips being  
21 fabricated on the semiconductor substrate.

22  
23 **Please add Claim 22.**

24  
25 22. **(New)** The method as recite in claim 9 wherein  
26 the semiconductor chips are positioned on an integrated  
27 circuit board.

1 Please add Claim 23.

2

3 23. (New) The system as recited in claim 15 wherein  
4 the transmitting semiconductor chip and the receiving  
5 semiconductor chip are fabricated on the same substrate.

6